

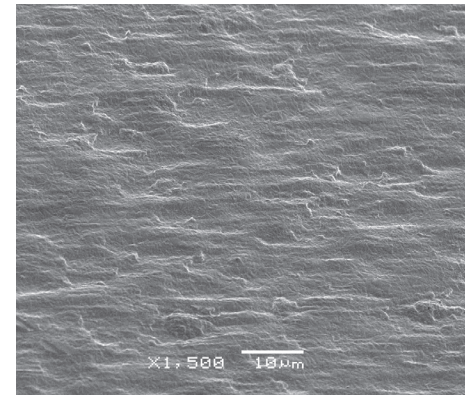
High reliability electrodeposited copper foil.

Applications:

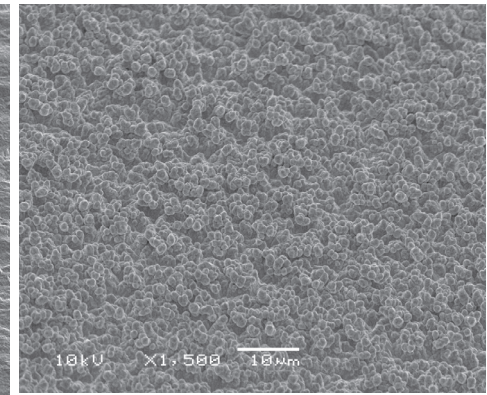
- Resistive layers

Features:

- IPC Grade III
- Treatment on matte side of the foil
- Designed for use in resistive layers



Untreated Drum Side
H oz. /18 µm (1500x)



Treated Matte Side
H oz. /18 µm (1500x)

Typical Values:

Attribute		Unit	Value			Reference
Thickness Designation			T	H	1	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	12	18	35	
		oz.	3/8	1/2	1	
Area Weight		g/m ²	106.8	152.5	305	IPC-TM-650-2.2.17
		g/254 in ²	17.5	25	50	
		oz./ft ²	0.375	0.5	1	
Roughness	Drum Side	µm	0.25	0.25	0.25	IPC-TM-650-2.4.18
		µ"	10	10	10	
	Matte Side	µm	5.08	5.08	6.35	
		µ"	200	200	250	
Tensile	Ambient	Kg/mm ²	42.2	42.2	38.7	IPC-TM-650-2.4.18
		Kpsi	60	60	55	
	180°C	Kg/mm ²	21.1	21.1	21.1	
		Kpsi	30	30	30	
Elongation	Ambient	%	6	8	15	IPC-TM-650-2.4.18
	180°C	%	8			

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